

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2793520

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JONGRYOUL KIM	03/03/2014
JINBAE KIM	03/13/2014
NAMSEOK KANG	03/14/2014
SANGGEUN CHO	03/13/2014
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	20 Yeouido-dong, Yeongdeungpo-gu
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Name:	INDUSTRY-UNIVERSITY COOPERATION FOUNDATION HANYANG UNIVERSITY ERICA CAMPUS
Street Address:	55, HANYANGDAEHAK-RO, SANGNOK-GU
City:	ANSAN-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14348507
CORRESPONDENCE DATA	
Fax Number:	(703)205-8050
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	0630-5886PUS1
NAME OF SUBMITTER:	MUSSIÉ B. BEYENE
SIGNATURE:	/Mussie B. Beyene/

PATENT

DATE SIGNED:	03/31/2014
Total Attachments: 3 source=2014-03-14_DecAssignment_0630-5886PUS1#page1.tif source=2014-03-14_DecAssignment_0630-5886PUS1#page2.tif source=2014-03-14_DecAssignment_0630-5886PUS1#page3.tif	

Application No.: 14/348,507

Filed on: March 28, 2014

Attorney Docket No.

0630-5886PUS1

BIRCH, STEWART, KOLASCH & BIRCH, LLP

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**DECLARATION AND ASSIGNMENT
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

Title of Invention ⇒ CORE-SHELL STRUCTURED NANOPARTICLE HAVING HARD-SOFT MAGNETIC
HETEROSTRUCTURE, MAGNET PREPARED WITH SAID NANOPARTICLE, AND PREPARING
METHOD THEREOF

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

Application not
Attached ⇒ This declaration is directed to the application attached hereto. If the application is not attached hereto, the
application is as identified by the attorney docket number as set forth above and/or the following:

Enter Appln. No. ⇒ United States Application Number or PCT International Appln. No. _____

Enter Filing Date ⇒ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,
Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain new and useful improvements described in the
application identified.

Insert Name
of Assignee(s) ⇒ WHEREAS, LG ELECTRONICS INC./INDUSTRY-UNIVERSITY COOPERATION FOUNDATION
HANYANG UNIVERSITY ERICA CAMPUS

Insert Address
of Assignee(s) ⇒ of 20 Yeouido-dong, Yeongdeungpo-gu, Seoul, Republic of Korea

55, Hanyangdaehak-ro, Sangnok-gu, Ansan-si, Gyeonggi-do, Republic of Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous
of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s)
that may be granted therefor in the United States of America and

Check Box if
Appropriate ⇒ ☐ in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged,
the undersigned has sold, assigned and transferred, and by these presents does (do) sell, assign and
transfer unto said Assignee the full and exclusive right to the said invention in the United States of
America, its territories, dependencies and possessions and the entire right, title and interest in and to any
and all Letters Patent(s) which may be granted therefor in the United States of America, its territories,
dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to
any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or
terms for which the same may be granted.

The undersigned agrees to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agrees to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agrees to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) or a grant of (a) valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grants the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

LEGAL NAME OF INVENTOR

Inventor's Name ⇒ Inventor: Jongryoul KIM

Date: March/3/'14

Inventor's Signature ⇒ Signature: 

An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use a separate form for each inventor; or check the box below and complete the attached page(s) to list additional inventors

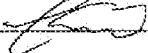
☒ Additional inventors are being named on the 1 supplemental sheet(s) attached hereto.

**SUPPLEMENTAL SHEET FOR
DECLARATION AND ASSIGNMENT**

ADDITIONAL INVENTOR(S)
Supplemental Sheet Page 1 of 1

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: Jinbae KIM Date: March 13/14

Inventor's Signature Signature: 

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: Namseok KANG Date: Mar 14 2014

Inventor's Signature Signature: 

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: Sanggeun CHO Date: March 13/14

Inventor's Signature Signature: 

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: _____ Date: _____

Inventor's Signature Signature: _____

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: _____ Date: _____

Inventor's Signature Signature: _____

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: _____ Date: _____

Inventor's Signature Signature: _____

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: _____ Date: _____

Inventor's Signature Signature: _____

LEGAL NAME OF JOINT INVENTOR, IF ANY

Inventor's Name Inventor: _____ Date: _____

Inventor's Signature Signature: _____